

# **PLASTIC PACKAGE BASE, AIR CAVITY TYPE PACKAGE AND THEIR MANUFACTURING METHODS**

Publication number: JP2004505450 (T)

Publication date: 2004-02-19

Inventor(s):

Applicant(s):

Classification:

- international: H01L23/02; H01L23/04; H01L23/055; H01L23/08;  
H01L23/10; H01L23/495; H01L23/496; H01L23/50;  
H01L23/02; H01L23/48; (IPC1-7): H01L23/50; H01L23/02;  
H01L23/05  
- European: H01L23/04; H01L23/055; H01L23/10; H01L23/495F;  
H01L23/498L

Application number: JP20020514786T 20010720

Priority number(s): KR20000042755 20000725; KR20000059051 20001007;  
WO2001KR01244 20010720

Also published as:

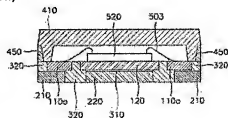
JP3733114 (B2)  
WO0209180 (A1)  
AU7281401 (A)  
JP2006041550 (A)  
CN1449583 (A)

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Abstract not available for JP 2004505450 (T)

Abstract of corresponding document: WO 0209180 (A1)

The plastic package base includes: a first lead frame including at least one first unit body comprising a first pad required for chip bonding and first leads acting as internal terminals, arranged around the first pad and spaced a predetermined distance away from the first pad; a second lead frame including at least one second unit body comprising a second pad and second leads acting as external terminals and bonded to the first lead frame so that the second pad and the second leads correspond to the first pad and first leads of the first lead frame; and a plastic body mold-shaped in spaces between the first and second lead frames so that the top surfaces of the first leads, the top surface of the first pad, the bottom surfaces of the second leads, and the bottom surface of the second pad are exposed on the surfaces of the plastic body and the top surface of the plastic body is not higher than the top surfaces of the first leads.



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